

Claim

- DI
1. Solid state substrate for DNA immobilizing with excellent thermal conductive characteristic for amplifying immobilized DNA.
 - Sub 2. Substrate as claimed in claim 1, wherein said substrate is diamond.
 - a 3. Substrate as claimed in claim 1 or 2, wherein said substrate is chemically modified.
 4. Substrate as claimed in ~~one of claims 1 through 3~~ ^{claim 1}, wherein said substrate has a polar group at terminal.
 - DI 5. Substrate as claimed in claim 4, wherein said polar radical is hydroxyl radical, carboxyl group, epoxy radical or amino radical.
 - Sub 6. Substrate as claimed in claim 5, wherein said carboxyl radical is connected on a surface of said substrate through ester linkage.
 7. Substrate as claimed in claim 5, wherein said carboxyl radical is connected on a surface of said substrate through amide linkage.
 8. Substrate as claimed in claim 5, wherein said carboxyl radical is introduced to a surface of said substrate with cylane coupling agent, titanium coupling agent or aluminum coupling agent.
 9. Substrate as claimed in claim 5, wherein said epoxy radical is introduced to a surface of said substrate with cylane coupling agent, titanium coupling agent or aluminum coupling agent.
 10. Substrate as claimed in claim 5, wherein said amino

radical is introduced to a surface of said substrate with cylane coupling agent, titanium coupling agent or aluminum coupling agent.

a 11. Chip for immobilizing DNA as claimed in claim ~~one~~ ¹ or
a ~~claims 1 to 10~~, wherein DNA is immobilized on said substrate.

D3 12. Method for amplifying DNA for substrate as claimed in claims 1 through 10 and chip as claimed in claim 11.

add B1
add D5